	<specification></specification>							
.			SPE Date	C.No. ASDIQ-SPE-056(02) 9: Oct.30,2020				
To :								
		CUSTOMER'S PRO	DUCT NAME					
	ASDI PRODUCT NAME:							
	SIPM0503C-SERIES							
	·							
RECEIPT	CONFIRMATION							
	UNCONDITIONAL C	CONSENT	CONDIT	IONAL CONSENT				
	APPR	OVED	CHEC	CKED				
ASDI SIGI								
	APPROVED Xianglong Li	CHECKED Liang Wang	PREPARED Jiayin Cai					



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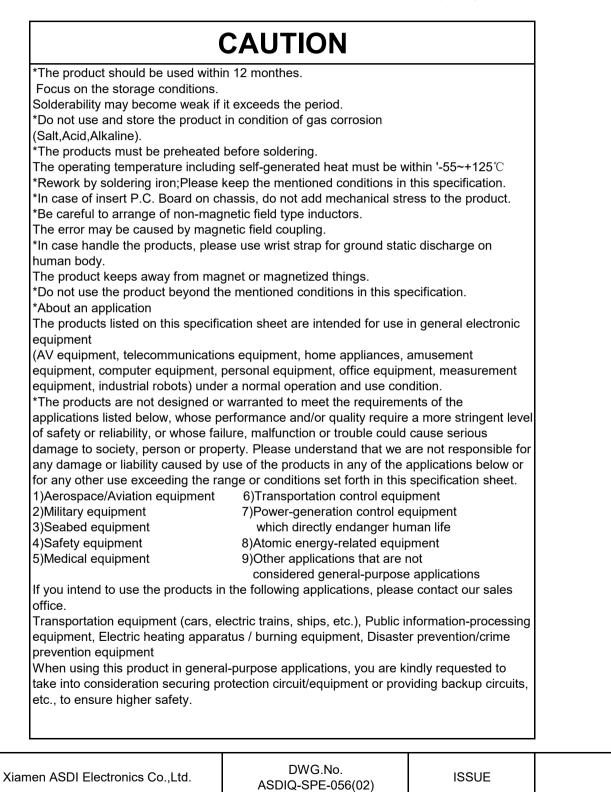
REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Mar.28,2019	New release	Xianglong Li	Liang Wang	Jiayin Cai
01	May.28,2020	Increased inductance value 5R6M	Xianglong Li	Liang Wang	Jiayin Cai
02	Oct.30,2020	ncreased inductance value 150M/220M	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.



CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
Each Corporation	SIPM0503C-SERIES	

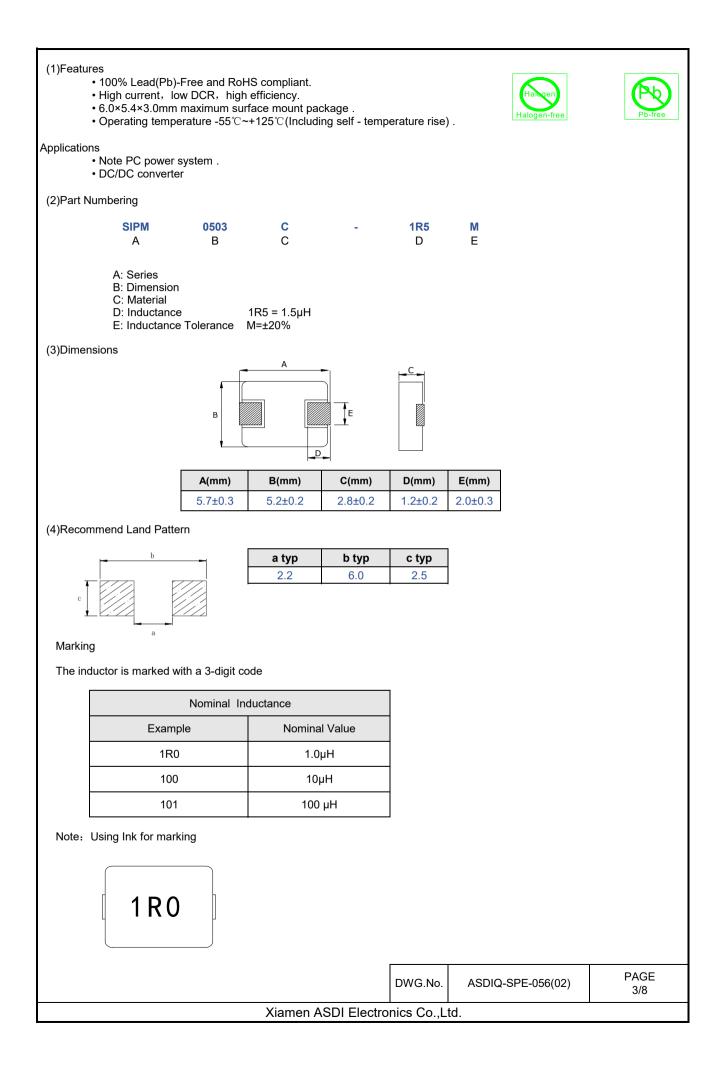
1.INDEX

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2.Manufacturing Location

China

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(5)Electrical Specifications

Table 1

	Inductance	DC Resistance	Saturation Current	Heating Rating Current
ASDI Part Number	L0(µH)	DCR (mΩ)	I sat(A)	Irms (A)
	±20% 100 kHz/1V	MAX.	TYP.	TYP.
SIPM0503C-R22M	0.22	4.40	21.0	15.5
SIPM0503C-R33M	0.33	5.00	18.0	14.0
SIPM0503C-R47M	0.47	7.40	16.0	12.0
SIPM0503C-R68M	0.68	12.0	14.0	8.50
SIPM0503C-R82M	0.82	13.0	12.5	8.00
SIPM0503C-1R0M	1.00	14.0	11.0	7.00
SIPM0503C-1R5M	1.50	25.0	10.0	6.00
SIPM0503C-2R2M	2.20	35.0	9.00	5.50
SIPM0503C-3R3M	3.30	38.0	8.00	5.00
SIPM0503C-4R7M	4.70	53.0	6.00	4.60
SIPM5030-5R6M	5.60	63.0	4.50	4.25
SIPM0503C-6R8M	6.80	76.2	4.30	4.00
SIPM0503C-100M	10.0	128	3.50	2.75
SIPM0503C-150M	15.0	190	2.60	2.10
SIPM0503C-220M	22.0	250	1.70	1.90

Notes:

- 1. All test data is referenced to 25 °C ambient
- Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)
- 3. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
- 4. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.

Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions

all affect the part temperature. Part temperature should be verified in the end application.

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(6)Structure and Components

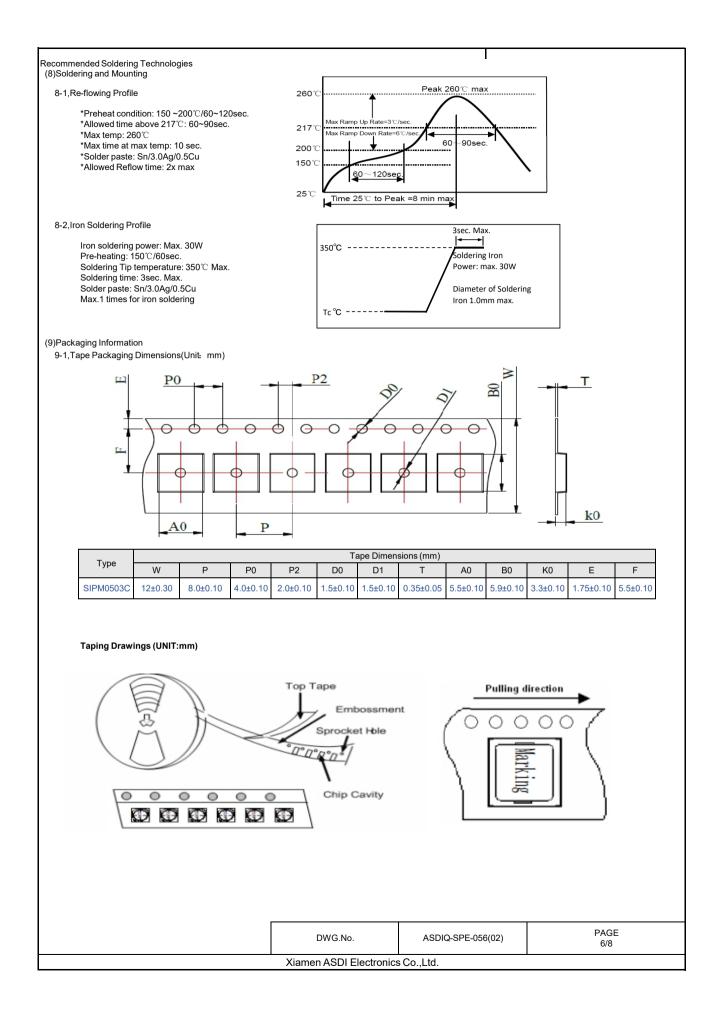
No.	Components	Material
1	Core	Carbonyl Powder
2	Wire	Polyester Wire or equivalent.
3	Clip	100% Pb free solder(Ni+SnPlating)
4	Paint	Epoxy resin
5	Ink	Halogen-free ketone

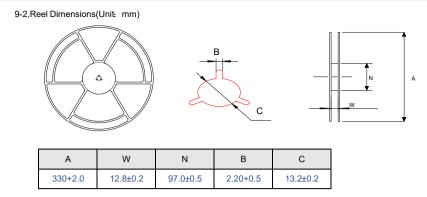


(7)Reliability Tests

	Mechanical Reliability						
No.	Test item	Performance	Test details				
1	Solderability	1. No case deformation or change in apperarance 2. New solder coverage more than 95%	1.Preheat: 155℃±5℃, 60S±2S 2.Solder: lead-free. 3.Temperature: 240℃±5℃, flux 3.0S±0.5S.				
2	Mechanical shock	1. No case deformation or change in apperarance 2. △L/Lo≦±10%	1. Acceleration: 100G 2. Pulse time:: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions				
3	Mechanical vibration	1.No case deformation or change in apperarance 2. △L/Lo≦±10%	 Reflow: 2times Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles Amplitude: 1.52 mm Directions: X,Y,Z Time: 12 cycle / direction 				
	Endurance and Reliability Test						
No.	Test item	Performance	Test details				
4	Thermal shock test	Inductance change: Within ± 10% Without distinct damage in appearance	 First -55°C for 30 minutes, last 125 °C for 30 minutes as 1 cycle. Go through 1000 cycles. Max transfer time is 3 minutes. Measured at room temperature after placing for 24±2 hours 				
5	Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85 [°] C,85 [°] RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours				
6	Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	 Temperature: -55 ± 2°C Time: 1000 hours Measured at room temperature after placing for 24±2 hours 				
7	High temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature: +125 ± 2℃ 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours				

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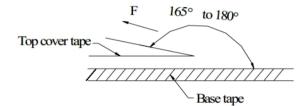
9-3, Packaging Quantity

Tures	Standard Quantity			
Туре	Reel	Inner box	Carton box	
SIPM0503C	2000 pcs / reel	4Reel / box (8000 pcs)	4 Middle boxes, (32,000 pcs)	

9-4, Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 $\ensuremath{\mathsf{N}}$



Label

9-5,Reel Label

- Label on the reel ·Customer's part Number ·Lot Number ·Quantity ·Date code
- Shipping Label •Customer's part Number •Manufacturer's part Number
- ·Quantity ·Date code

9-6,Inner Box

Packing Type	A (mm)	B (mm)	C (mm)
Inner Box	335	70	340

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		Packing Type	A (mm)	B (mm)	C (mm)
+	Label	Туре	360	360	360
c Carton				-	
xxxxxxxx Electronics	s Co., Ltd.				
Note					
 Storage Conditions To maintain the solderability of terr 	ninal electrodes:				
1. ASDI products meet IPC/JEDEC 2. Temperature and humidity cond	C J-STD-020D standard-N		5%		
Max. 3. Recommended products should					
4. The packaging material should the Transportation					
1. Products should be handled with	າ care to avoid damage or	r contamination from			
perspiration and skin oils. 2. The use of tweezers or vacuum	pick up is strongly recom	mended for individual			
components. 3. Bulk handling should ensure tha	t abrasion and mechanica	al shock are minimized	l.		

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